



Pin Definition:

1. Gate 2. Drain

3. Source

VDS (V) RDS(on)(Ω) ID (A) 650 0.8 @ VGS=10V 6

General Description

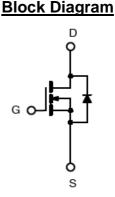
The TSM12N65 N-Channel enhancement mode Power MOSFET is produced by planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

Features

- Low R_{DS(ON)} 0.68Ω (Typ.)
- Low gate charge typical @ 41nC (Typ.)
- Low Crss typical @ 14.6pF (Typ.)
- Fast Switching

Ordering Information

Part No.	Package	Packing
TSM12N65CI C0	ITO-220	50pcs / Tube



N-Channel MOSFET

Absolute Maximum Rating (Ta = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit V	
Drain-Source Voltage		V _{DS}		650
Gate-Source Voltage		V _{GS}	±30	V
Continuous Durin Current	Tc = 25°C	- I _D	12	А
Continuous Drain Current	$Tc = 100^{\circ}C$		4.5	А
Pulsed Drain Current *		I _{DM}	48	А
Single Pulse Avalanche Energy (Note 2)		E _{AS}	273	mJ
Avalanche Current (Repetitive) (Note 2		I _{AS}	12	А
Single Pulse Avalanche Energy (Note 1)		E _{AR}	7.6	mJ
Avalanche Current (Repetitive) (Note 1)		I _{AR}	12	А
Total Power Dissipation @ $T_C = 25^{\circ}C$		P _{TOT}	45	W
Operating Junction Temperature		TJ	150	°C
Storage Temperature Range		T _{STG}	-55 to +150	°C

Note: Limited by maximum junction temperature

Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance - Junction to Case	RƏ _{JC}	2.7	°C/W
Thermal Resistance - Junction to Ambient	Rθ _{JA}	62.5	°C/W

Notes: Surface mounted on FR4 board t \leq 10sec



Electrical Specifications (Ta = 25°C unless otherwise noted)

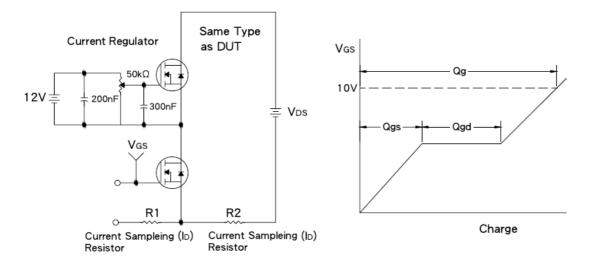
Parameter	Conditions	Symbol	Min	Тур	Max	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_{D} = 250uA$	BV _{DSS}	650			V	
Drain-Source On-State Resistance	$V_{GS} = 10V, I_{D} = 6A$	R _{DS(ON)}		0.68	0.8	Ω	
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 uA$	V _{GS(TH)}	2.0		4.0	V	
Zero Gate Voltage Drain Current	$V_{DS} = 650 V, V_{GS} = 0 V$	I _{DSS}			1	uA	
Gate Body Leakage	$V_{GS} = \pm 30V, V_{DS} = 0V$	I _{GSS}			±100	nA	
Forward Transfer Conductance	$V_{DS} = 10V, I_{D} = 6A$	g _{fs}		10		S	
Dynamic ^b							
Total Gate Charge		Qg		41		nC	
Gate-Source Charge	$V_{DS} = 480V, I_D = 12A,$	Q _{gs}		13			
Gate-Drain Charge	V _{GS} = 10V	Q _{gd}		10.5			
Input Capacitance		C _{iss}		2162		pF	
Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$	C _{oss}		183			
Reverse Transfer Capacitance	f = 1.0MHz	C _{rss}		14.6			
Switching ^c							
Turn-On Delay Time		t _{d(on)}		30			
Turn-On Rise Time	$V_{GS} = 10V, I_D = 12A,$	t _r		85		- 0	
Turn-Off Delay Time	V_{DD} = 300V, R_G =25 Ω	t _{d(off)}		140		nS	
Turn-Off Fall Time		t _f		90			
Source-Drain Diode Ratings and Characteristic							
Source Current	Integral reverse diode in	I _S			12	А	
Source Current (Pulse)	the MOSFET	I _{SM}			48	А	
Diode Forward Voltage	$I_{S} = 12A, V_{GS} = 0V$	V _{SD}			1.4	V	
Reverse Recovery Time	$V_{GS} = 0V, I_{S} = 12A,$	t _{fr}		510		nS	
Reverse Recovery Charge	dI _F /dt = 100A/us	Q _{fr}		4.3		uC	

Note 1: Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature **Note 2:** $V_{DD} = 50V$, $I_{AS}=12A$, L=3.5mH, $R_G=25\Omega$, Starting $T_J=25^{\circ}C$ **Note 3:** Pulse test: pulse width ≤300uS, duty cycle ≤2%

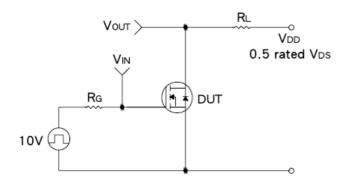
Note 4: Essentially Independent of Operating Temperature

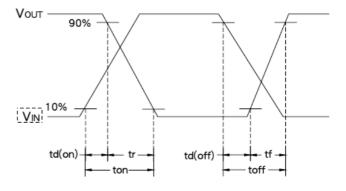


Gate Charge Test Circuit & Waveform

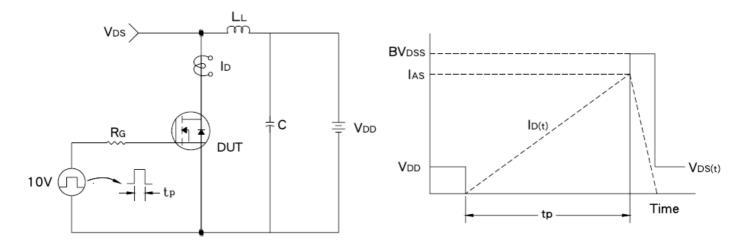


Resistive Switching Test Circuit & Waveform



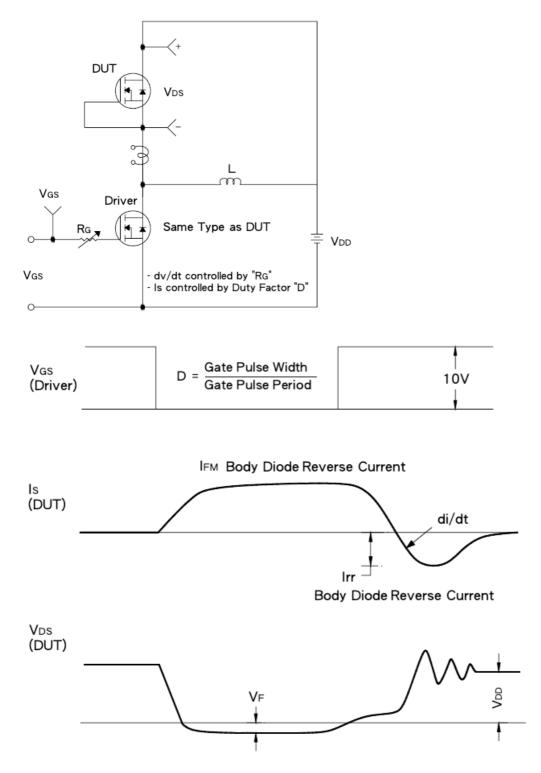


E_{AS} Test Circuit & Waveform





Diode Reverse Recovery Time Test Circuit & Waveform

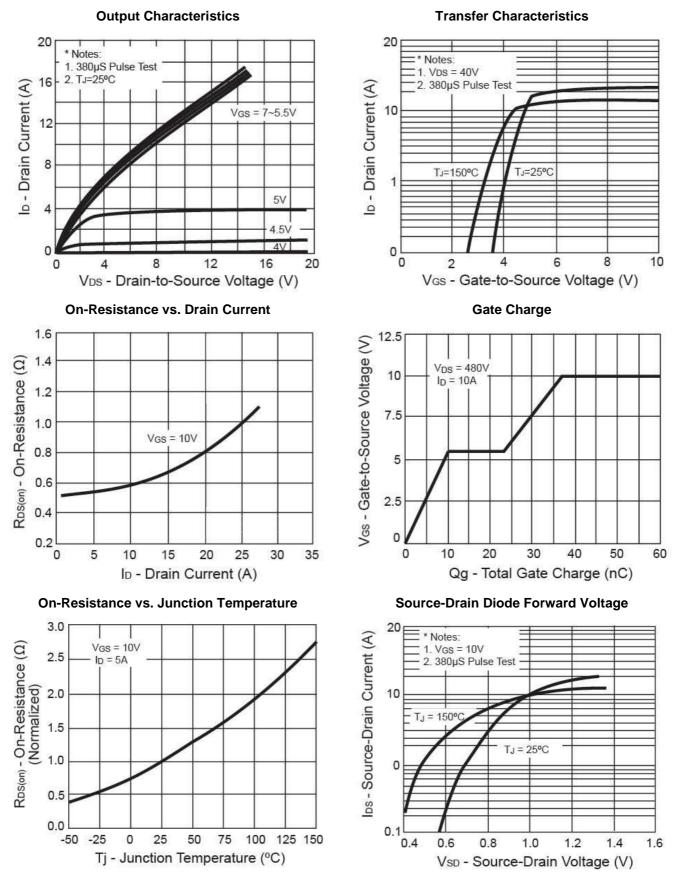


TAIWAN MICONDUCTOR COMPLIANCE

TSM12N65 650V N-Channel Power MOSFET

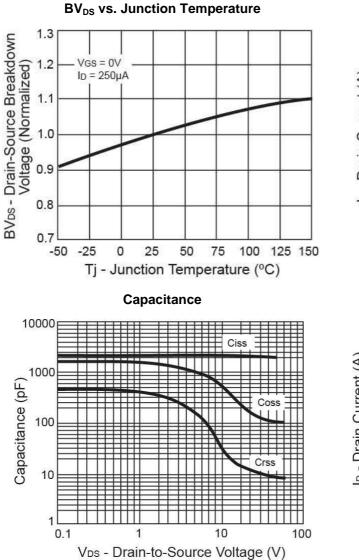


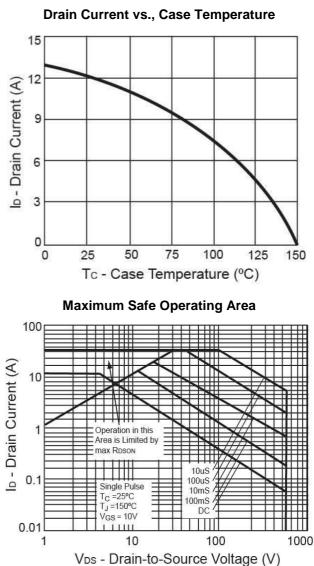
Electrical Characteristics Curve (Ta = 25°C, unless otherwise noted)





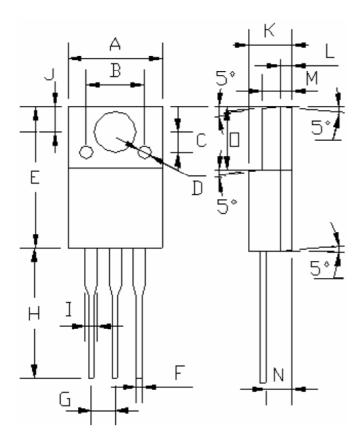
Electrical Characteristics Curve (Ta = 25°C, unless otherwise noted)







ITO-220 Mechanical Drawing



	ITO-220 DIMENSION						
DIM	MILLIM	MILLIMETERS		INCHES			
DIIVI	MIN	MAX	MIN	MAX			
Α	10.04	10.07	0.395	0.396			
В	6.20	(typ.)	0.244	(typ.)			
С	2.20	(typ.)	0.087 (typ.)				
D	∮ 1.4 0	§ 1.40 (typ.)		5 (typ.)			
Е	15.0	15.20	0.591	0.598			
F	0.52	0.54	0.020	0.021			
G	2.35	2.73	0.093	0.107			
Н	13.50	13.55	0.531	0.533			
Ι	1.11	1.49	0.044	0.058			
J	2.60	2.80	0.102	0.110			
K	4.49	4.50	0.176	0.177			
L	1.15 (typ.)		0.045 (typ.)				
Μ	3.03	3.05	0.119	0.120			
Ν	2.60	2.80	0.102	0.110			
0	6.55	6.65	0.258	0.262			

Marking Diagram



- **Y** = Year Code
- M = Month Code
 (A=Jan, B=Feb, C=Mar, D=Apl, E=May, F=Jun, G=Jul, H=Aug, I=Sep, J=Oct, K=Nov, L=Dec)
- L = Lot Code



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